

Amendments to the Claims:

12. (Currently Amended) A mobile phone structure that can attenuate undesirable electro-magnetic waves prevalent at abrupt discontinuities of metallized areas within the mobile phone during normal operation of the mobile phone, the mobile phone structure comprising:

an impedance layer comprised of:

a ~~non-ferrous~~ metallic layer substantially covering the metallized areas wherein the ~~non-ferrous~~ metallic layer reduces the effect of undesirable electro-magnetic waves on the side of the ~~non-ferrous~~ metallic layer opposite the substantially covered metallized areas; and

a dielectric substrate layer having inner and outer surfaces coupled with the metallic layer.

13. (Canceled)

14. (Currently Amended) The mobile phone structure of claim ~~13~~ 12 wherein the ~~non-ferrous~~ metallic layer is coupled to the inner surface of the dielectric substrate layer.

15. (Currently Amended) The mobile phone structure of claim ~~13~~ 12 wherein the ~~non-ferrous~~ metallic layer is coupled to the outer surface of the dielectric substrate layer.

16. (Currently Amended) The mobile phone structure of claim 12 wherein the impedance layer further comprises multiple dielectric substrate layers wherein the ~~non-ferrous~~ metallic layer is buried between a pair of dielectric substrate layers.

17. (Previously Presented) A mobile phone structure that can attenuate undesirable electro-magnetic waves prevalent at abrupt discontinuities of metallized areas within the mobile phone during normal operation of the mobile phone, the mobile phone structure comprising:

an impedance layer comprised of a resistive layer substantially covering the metallized areas wherein the resistive layer reduces the effect of undesirable electro-magnetic waves on the side of the resistive layer opposite the substantially covered metallized areas.

18. (Previously Presented) The impedance layer of claim 17 further comprising a dielectric substrate layer having inner and outer surfaces coupled with the resistive layer.

19. (Previously Presented) The impedance layer of claim 18 wherein the resistive layer is coupled to the inner surface of the dielectric substrate layer.

20. (Previously Presented) The impedance layer of claim 18 wherein the resistive layer is coupled to the outer surface of the dielectric substrate layer.

21. (Previously Presented) The impedance layer of claim 17 further comprising multiple dielectric substrate layers wherein the resistive layer is buried between a pair of dielectric substrate layers.

22. (Currently Amended) A mobile phone structure that can attenuate undesirable electro-magnetic waves prevalent at abrupt discontinuities of metallized areas within the mobile phone during normal operation of the mobile phone, the mobile phone structure comprising:

an impedance layer comprised of:

a ~~non-ferrous~~ metallic layer; and

a resistive layer coupled with the non-ferrous metallic layer and integrated into the front cover of the mobile phone,

wherein the ~~non-ferrous~~ metallic layer guides undesirable electro-magnetic waves into the resistive layer where the undesirable electro-magnetic waves are attenuated thereby reducing the effect the undesirable electro-magnetic waves prevalent at abrupt discontinuities of metallized areas.